

Title (en)

Method for plating and plating solution thereof

Title (de)

Verfahren zum Plattieren und Plattierungslösung

Title (fr)

Procédé de placage et solution de placage

Publication

EP 1439244 A2 20040721 (EN)

Application

EP 04447010 A 20040114

Priority

- EP 04447010 A 20040114
- EP 03447008 A 20030114

Abstract (en)

A solution is described, in particular for electroless deposition of a metal on a polyimide substrate. The solution from which the metal is deposited, comprises a source of metal ions; a reducing agent; an additive to adjust the pH of said bath to a predetermined value; and an aromatic sulfonic acid. The solution is used in a method for electroless deposition of a metal onto a substrate wherein the substrate preferably comprises polyimide exposed at a surface thereof. The method of the present invention provides a metal layer which shows good adhesion towards the polyimide substrate and which is very smooth and does not need any additional smoothening treatment. <IMAGE>

IPC 1-7

C23C 18/31; **C23C 18/48**; **C23C 18/40**

IPC 8 full level

C23C 18/31 (2006.01); **C23C 18/40** (2006.01); **C23C 18/48** (2006.01)

CPC (source: EP)

C23C 18/31 (2013.01); **C23C 18/40** (2013.01); **C23C 18/48** (2013.01)

Cited by

US5476660A

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

EP 1439244 A2 20040721; **EP 1439244 A3 20050209**

DOCDB simple family (application)

EP 04447010 A 20040114